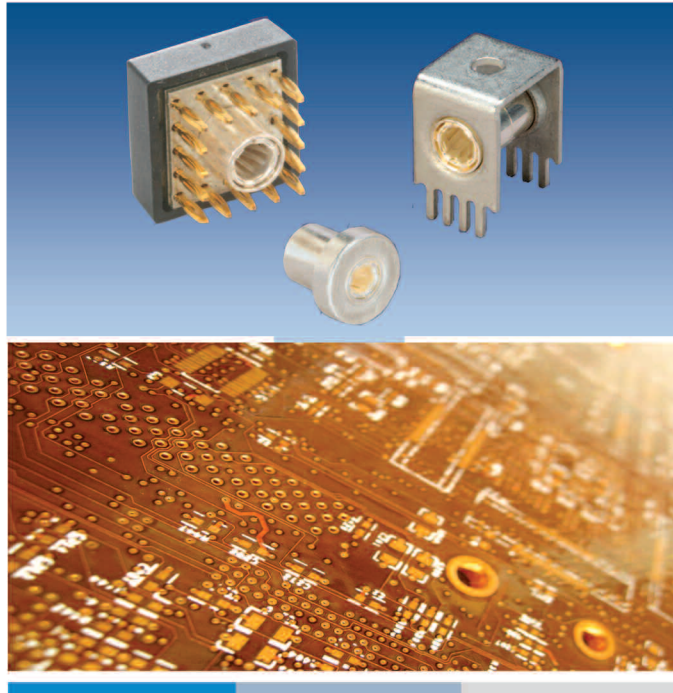


Amphenol



Amphenol® Industrial RADSOK® Products for Printed Circuit Boards

The Amphenol RADSOK® solution offers options for high current single-point connections with a compact footprint design that can supply up to 120 Amp to the board. The hyperbolic grid contact provides more surface area with many points of contact for heat dissipation at the pin and socket interface. This lowers temperature rise and reduces potential failures. RADSOK® PCB products are designed to be applied manually by press-fit or by a re-flow solder process eliminating the need for additional wires and/or special crimp tools.

RADSOK® PCB PowerBlok™ provides a high current single-point connection of up to 70 Amps to the PCB utilizing our custom 3.0mm RADSOK® design. The compliant pins are press-fit into the board to secure a solid connection and even signal flow. The radial design ensures many points of contact, reduces failure modes, eliminates burn-outs and possible stress fractures.

RADSOK® PCB RADSERT™ provides high power to board interconnect in a small package. The RADSERT™ brings power to the board from busbars suspended above the board and all of the board components. Pins from the busbar plug into the RADSOK's® which are installed by press fitting the RADSOK® into the RADSERT™.

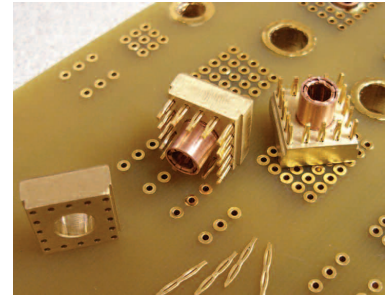
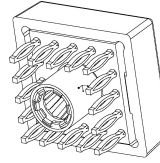
RADSOK® PCB PGY™ is an orthogonal card edge connector series available in 3.6mm and 5.7mm contact sizes. The 5.7mm is the highest current board level product rated to 120 amperes. Connection to the board is through a solder reflow process. The busbar pin will mate horizontally with the RADSOK® slightly above the board.

RADSOK® PCB PowerBlok™

- High power to board interconnect in a small package
- Compact footprint 0.618" x 0.618"
- 3.0mm RADSOK® carries up to 70 amperes
- Backplane power interface with compliant pins for signals
- Touchproof cover
- Radial design ensures many points of contact
- Reduces failure modes, eliminates burn outs
- No threaded fasteners
- No special crimp tools required
- Eliminates possible stress fractures in board
- Faster through-put
- RoHs compliant

Sample part number:

C10-639323-000 designates a 3.0mm PowerBlok with compliant pins.



High power density in a small footprint (approx. 1/2" x 1/2") Tooled to 3.0mm (70 amp) size

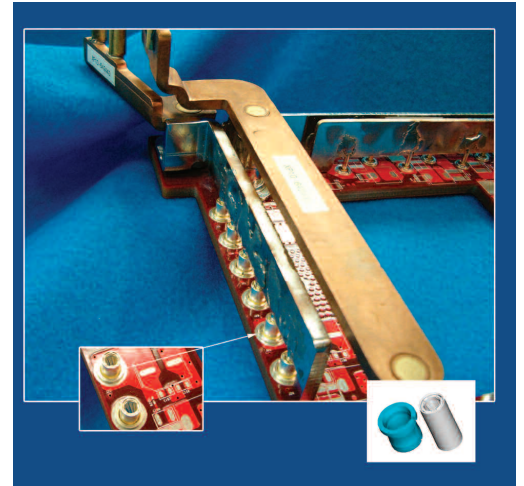
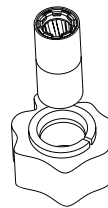
RADSOK® PCB RADSERT™

- High power to board interconnect in a small package
- Hyperbolic socket design ensures many points of contact
- Solder version or pre-loaded RADSERTS are installed during board fabrication
- 2.4mm RADSERT carries up to 35 Amps
- 3.6mm RADSERT carries up to 70 Amps
- Board thicknesses of .250" +/- .025"
- No special crimp tools required
- No threaded fasteners
- Eliminates risk of PTH cracking or delamination in board
- Faster through-put
- RoHs compliant

Sample part numbers:

C10-642495-241 designates 2.4mm RADSERT (solder)

C10-639772-001 designates 2.4mm RADSERT (one piece pre-loaded)



RADSOK® PCB PGY™

- Orthogonal connection between card edge and busbar/backplane
- Compact footprint
- Legs of the PGY dissipate high power evenly
- 5.7mm carries up to 120 Amps
- 3.6mm carries up to 70 Amps
- No threaded fasteners
- No special crimp tools required
- RADSOK's highest power to board level product
- Faster through-put
- RoHs compliant

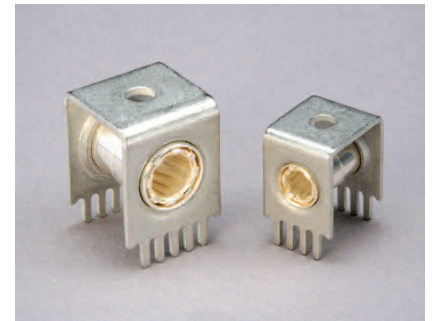
Sample part numbers:

C10-639800-001 designates 5.7mm PCB mount RADSOK®, horizontal, solder, silver plated

Dimensions: .563" (L) x .551" (D) x .791" (OAH) - (.653" above board and .138" into PCB)

C10-639801-001 designates PCB mount RADSOK®, horizontal, solder, silver plated

Dimensions: .480" (L) x .400" (D) x .630" (OAH) - (.492" above board and .138 into PCB)



Amphe-Power with RADSOK® Sockets Contact Ratings

Size 12	35 Amps
Size 8	70 Amps
Size 4	120 Amps
Size 0	250 Amps

Notice: Specifications are subject to change without notice. Contact your nearest Amphenol Corporation Sales Office for the latest specifications. All statements, information and data given herein are believed to be accurate and reliable but are presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suggestions concerning possible use of our products are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should assume that all safety measures are indicated or that other measures may not be required. Specifications are typical and may not apply to all connectors.

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